

Features

- N-Channel
40V/6.6A,
 $R_{DS(ON)} = 21\text{m}\Omega$ (Typ.) @ $V_{GS}=10\text{V}$
- P-Channel
-40V/-4.6A,
 $R_{DS(ON)} = 46\text{m}\Omega$ (Typ.) @ $V_{GS}=-10\text{V}$
- Very low on-resistance
- Fast Switching

Applications

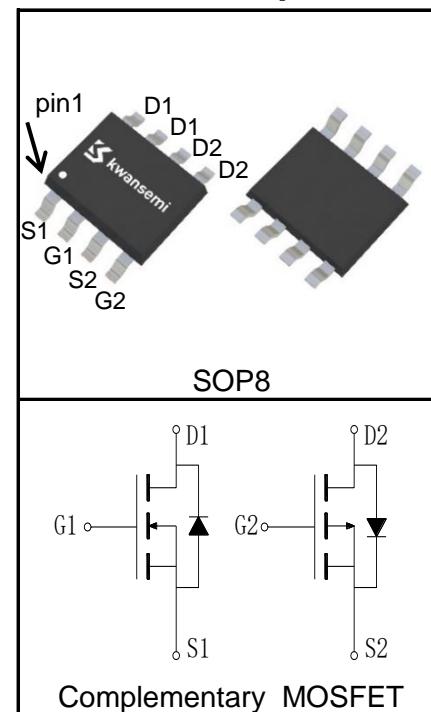
- Load Switch



Halogen-Free

Absolute Maximum Ratings

Symbol	Parameter	N-Channel	P-Channel	Unit
Common Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)				
V_{DSS}	Drain-Source Voltage	40	-40	V
V_{GSS}	Gate-Source Voltage	± 20	± 20	
T_J	Maximum Junction Temperature	150	150	$^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	-55 to 150	$^\circ\text{C}$
I_S	Diode Continuous Forward Current $T_C=25^\circ\text{C}$	1.6	-1.6	A
Mounted on Large Heat Sink				
$I_{DP}^{(1)}$	Pulse Drain Current	$T_A=25^\circ\text{C}$	26	-18
$I_D^{(2)}$	Continuous Drain Current@ $T_C(V_{GS}=\pm 10\text{V})$	$T_A=25^\circ\text{C}$	6.6	-4.6
		$T_A=70^\circ\text{C}$	5.2	-3.6
P_D	Maximum Power Dissipation@ T_C	$T_A=25^\circ\text{C}$	2	2
		$T_A=70^\circ\text{C}$	1.3	1.3
$R_{\theta JL}$	Thermal Resistance-Junction to Lead	40	40	$^\circ\text{C/W}$
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	62.5	62.5	$^\circ\text{C/W}$
Drain-Source Avalanche Ratings				
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	20	30	mJ



Electrical Characteristics ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	KS4640HB			Unit	
			Min.	Typ.	Max.		
Static Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=250\mu\text{A}$	N	40		V	
		$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=-250\mu\text{A}$	P	-40			
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	N		1	μA	
		$T_J=125^\circ\text{C}$			30		
		$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$	P		-1		
		$T_J=125^\circ\text{C}$			-30		
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=250\mu\text{A}$	N	1.1	1.5	2.3	V
		$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=-250\mu\text{A}$	P	-1.1	-1.5	-2.3	
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	N			± 100	nA
		$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	P			± 100	
$R_{\text{DS}(\text{ON})}^{(5)}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{DS}}=4\text{A}$	N		21	26	$\text{m}\Omega$
		$V_{\text{GS}}=-10\text{V}, I_{\text{DS}}=-4\text{A}$	P		46	55	
		$V_{\text{GS}}=4.5\text{V}, I_{\text{DS}}=3\text{A}$	N		24	31	
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{DS}}=-3\text{A}$	P		57	75	
Diode Characteristics							
$V_{\text{SD}}^{(5)}$	Diode Forward Voltage	$I_{\text{SD}}=4\text{A}, V_{\text{GS}}=0\text{V}$	N		0.81	1.2	V
		$I_{\text{SD}}=-4\text{A}, V_{\text{GS}}=0\text{V}$	P		-0.84	-1.2	
t_{rr}	Reverse Recovery Time	N-Channel $I_{\text{SD}}=4\text{A}, dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	N		9		ns
			P		10		
Q_{rr}	Reverse Recovery Charge	P-Channel $I_{\text{SD}}=-4\text{A}, dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	N		11		nC
			P		12		
Dynamic Characteristics ⁽⁶⁾							
R_{G}	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	N		4.3		Ω
			P		13		
C_{iss}	Input Capacitance	N-Channel $V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V},$ Frequency=1.0MHz	N		700		pF
			P		740		
C_{oss}	Output Capacitance	P-Channel $V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-20\text{V},$ Frequency=1.0MHz	N		50		pF
			P		55		
C_{rss}	Reverse Transfer Capacitance		N		40		pF
			P		45		

Electrical Characteristics ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)

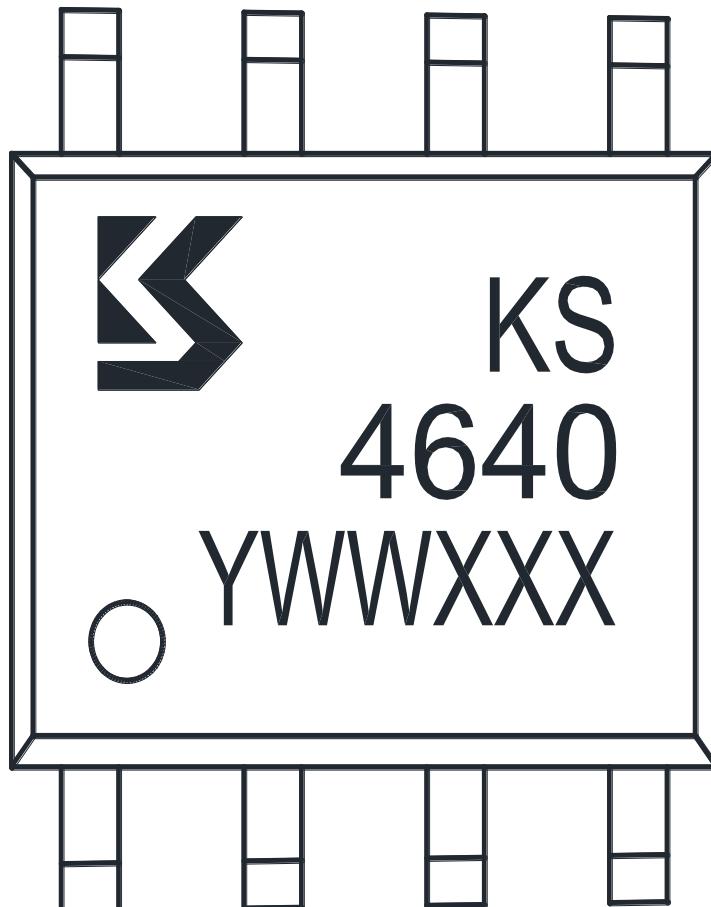
Symbol	Parameter	Test Condition	KS4640HB			Unit	
			Min.	Typ.	Max.		
Dynamic Characteristics^⑥							
$t_{d(ON)}$	Turn-on Delay Time	N-Channel $V_{DD}=20\text{V}$, $I_{DS}=4\text{A}$, $V_{GEN}=10\text{V}$, $R_G=3\Omega$	N	9		ns	
			P	11			
			N	15			
			P	19			
	Turn-on Rise Time	P-Channel $V_{DD}=-20\text{V}$, $I_{DS}=-4\text{A}$, $V_{GEN}=-10\text{V}$, $R_G=3\Omega$	N	27			
			P	33			
			N	12			
			P	15			
Gate Charge Characteristics^⑥							
Q_g	Total Gate Charge	N-Channel $V_{DS}=20\text{V}$, $V_{GS}=10\text{V}$, $I_{DS}=4\text{A}$	N	15		nC	
			P	17			
			N	1.6			
			P	1.9			
Q_{gs}	Gate-Source Charge	P-Channel $V_{DS}=-20\text{V}$, $V_{GS}=-10\text{V}$, $I_{DS}=-4\text{A}$	N	2.6			
			P	2.8			
Q_{gd}	Gate-Drain Charge						

Notes:

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature.
- ③When mounted on 1 inch square copper board, $t \leq 10\text{sec}$. The value in any given application depends on the user's specific board design.
- ④Limited by T_{Jmax} . Starting $T_J = 25^\circ\text{C}$, N Channel: $I_{ASmax} = 9\text{A}$, $L = 0.5\text{mH}$, $V_{DD} = 24\text{V}$, $R_G = 25\Omega$, $V_{GS} = 10\text{V}$, Part not recommended for use above this value. P-Channel: $I_{ASmax} = -11\text{A}$, $L = 0.5\text{mH}$, $V_{DD} = -24\text{V}$, $R_G = 25\Omega$, $V_{GS} = -10\text{V}$, Part not recommended for use above this value.
- ⑤Pulse test; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS4640HB	SOP8	Tape&Reel	3000	13"	12mm

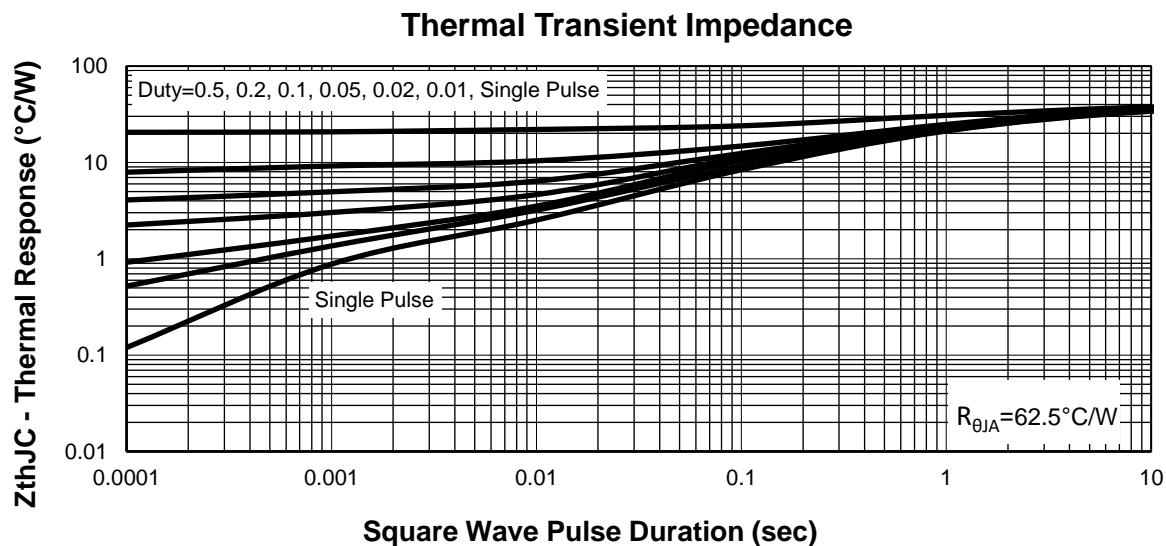
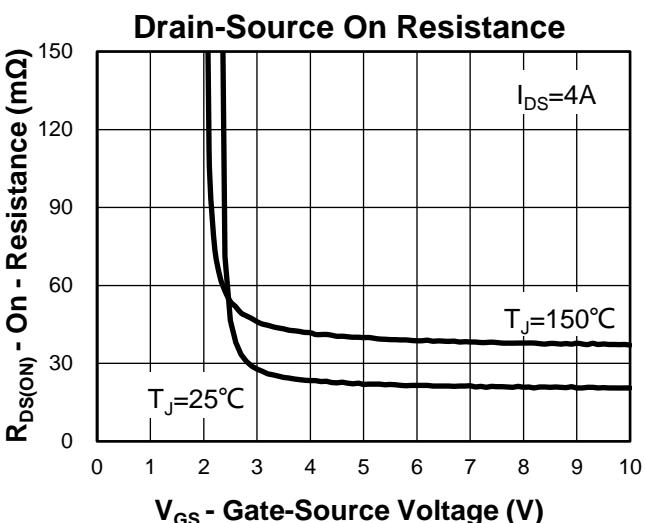
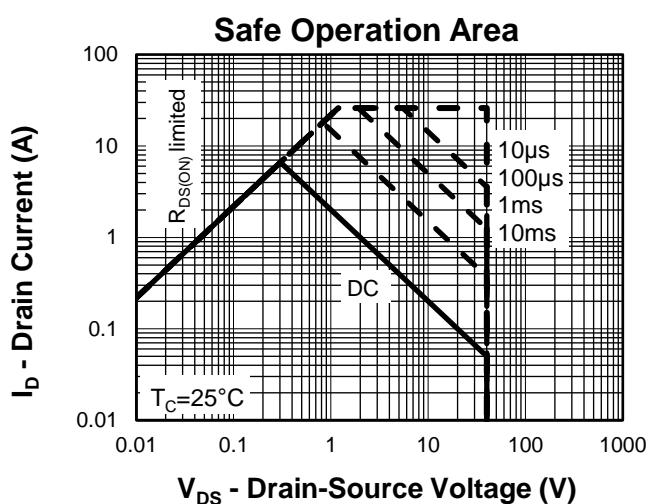
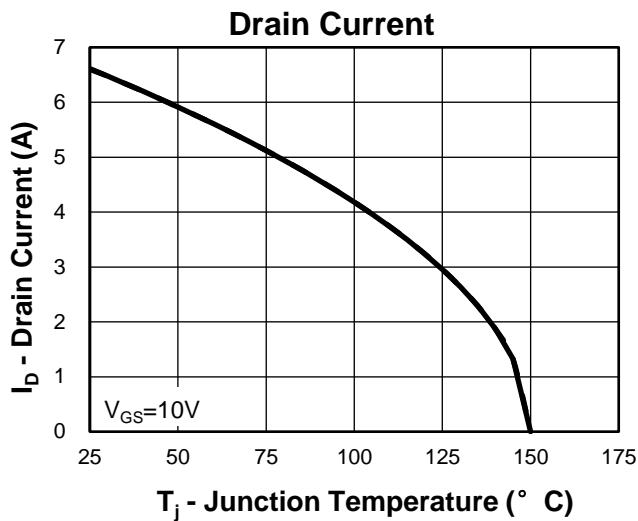
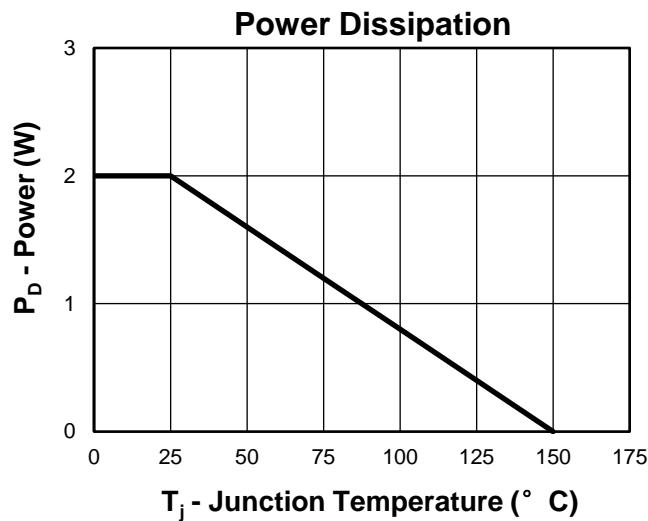


1st Line: Kwansemi LOGO, Kwansemi Code(KS)

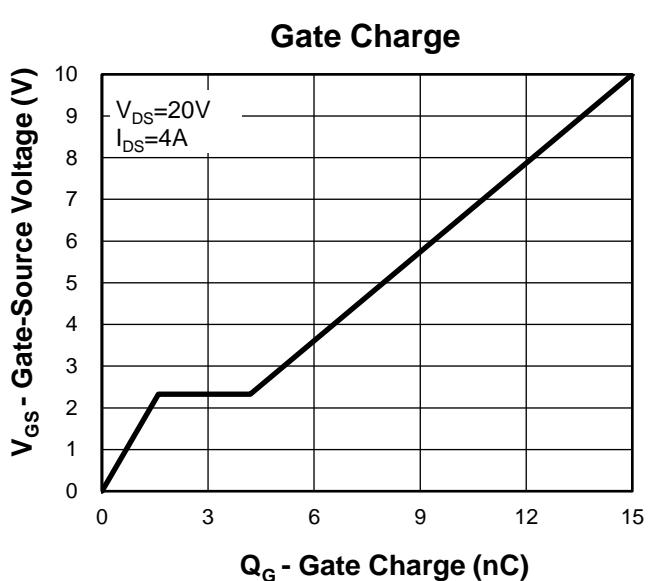
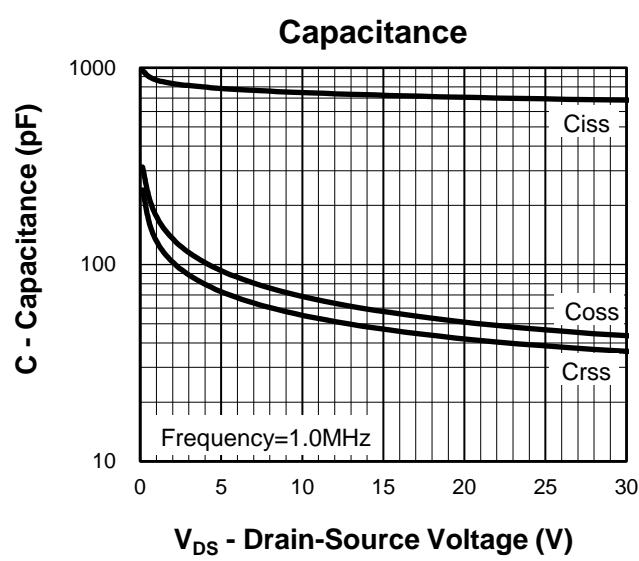
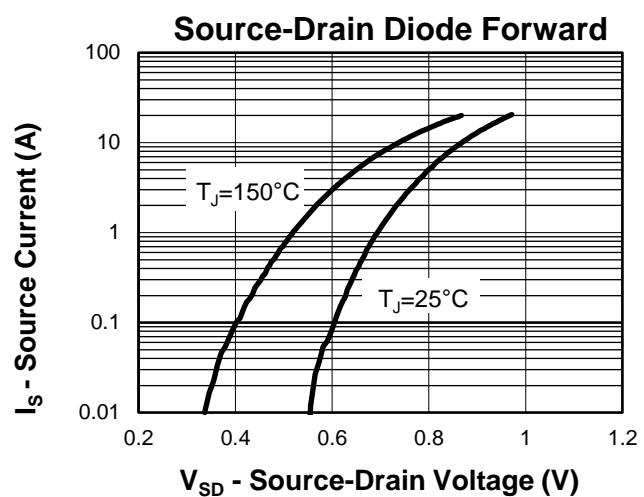
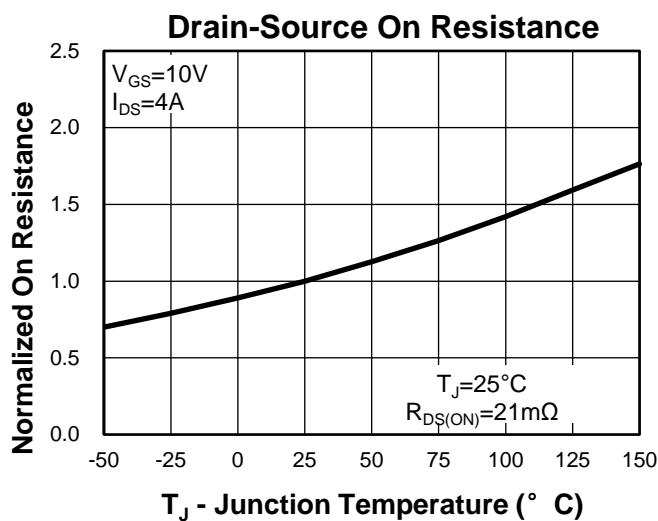
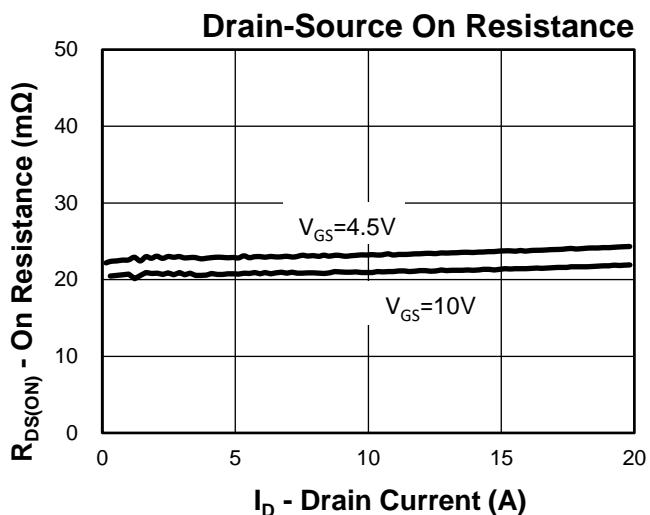
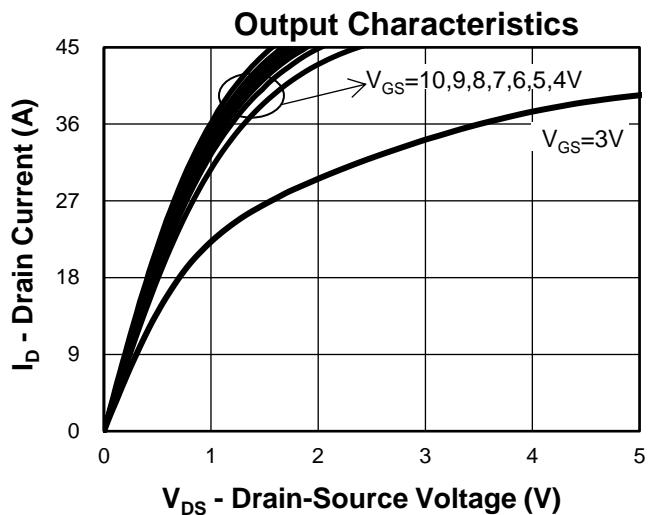
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3rd Line: Lot Number(YWWXXX)

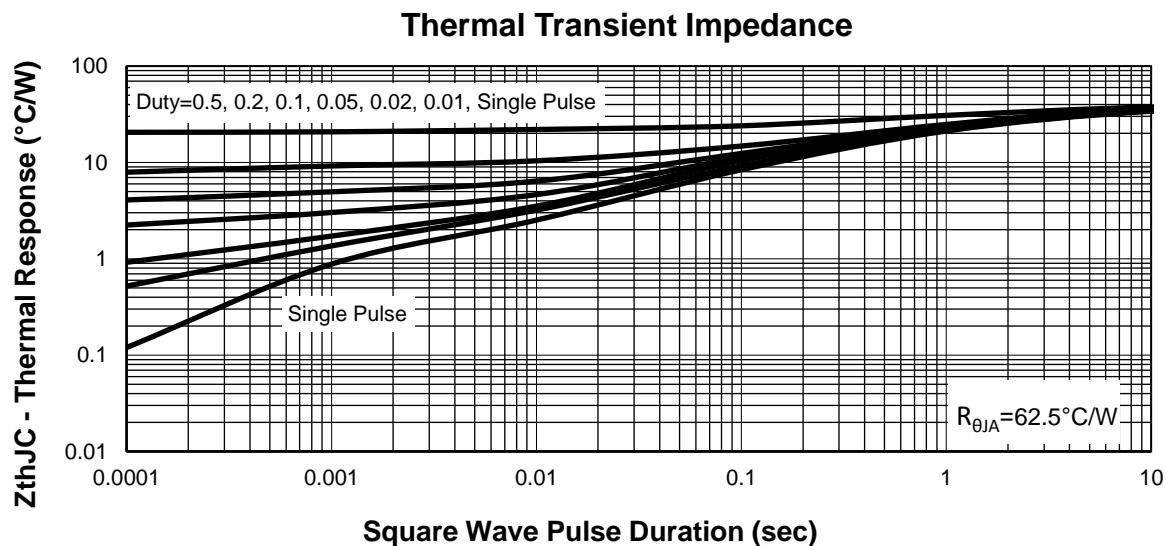
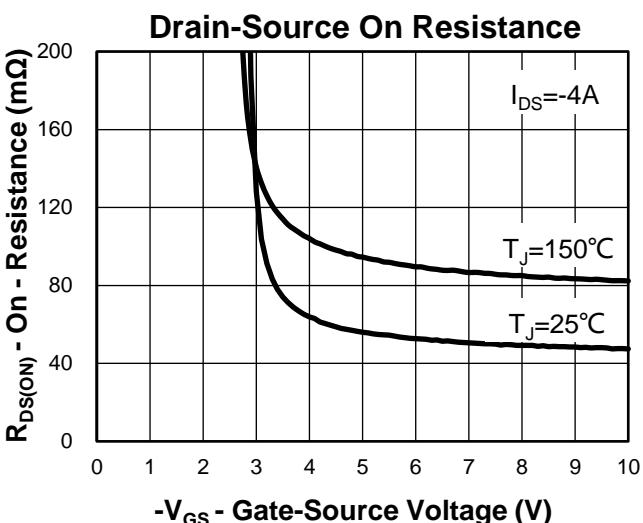
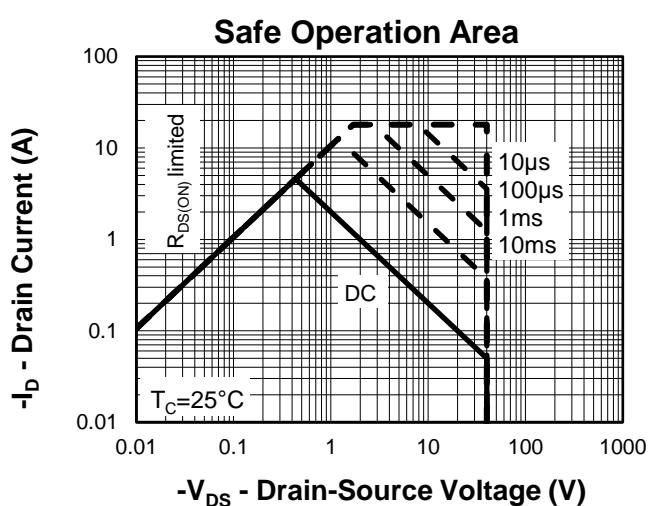
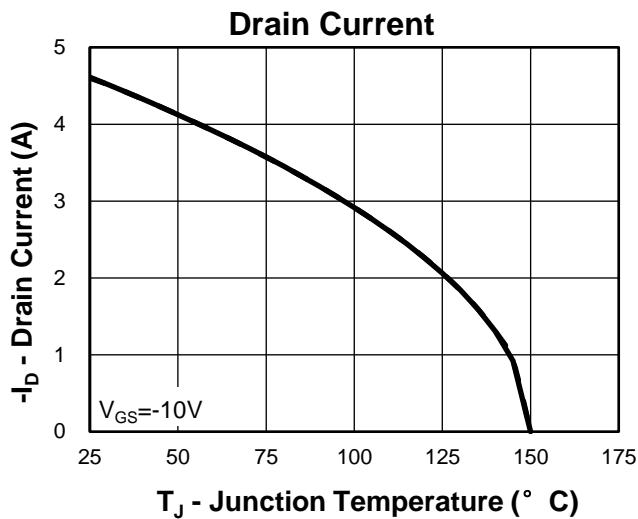
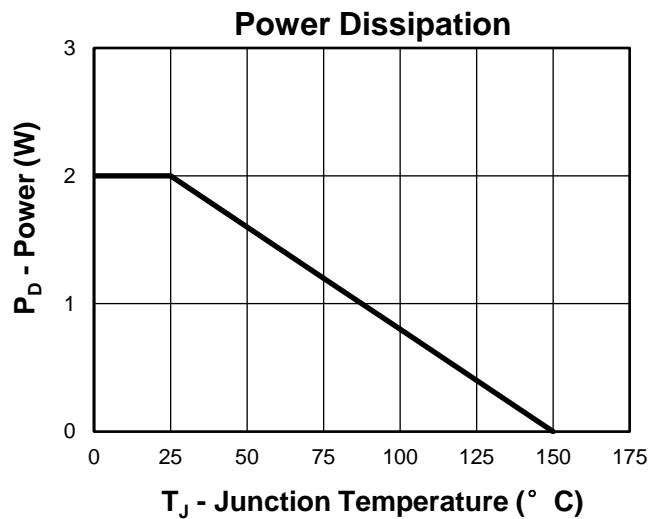
Typical Characteristics(N-Channel)



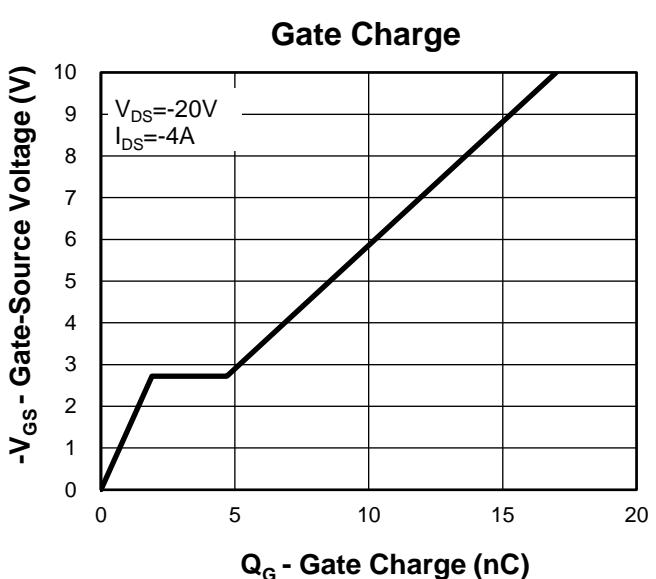
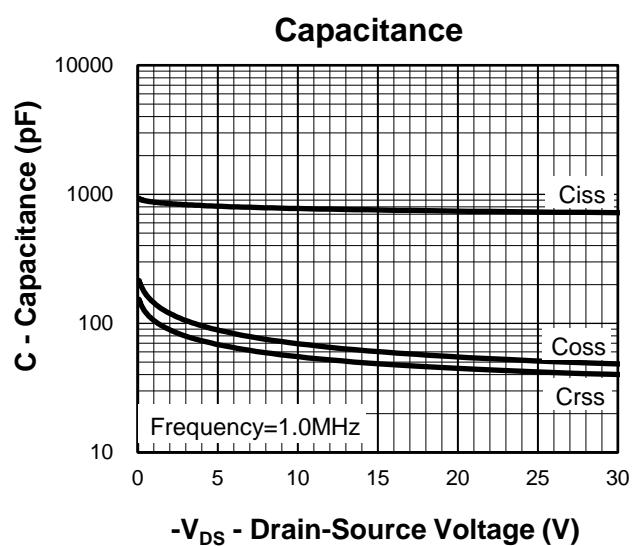
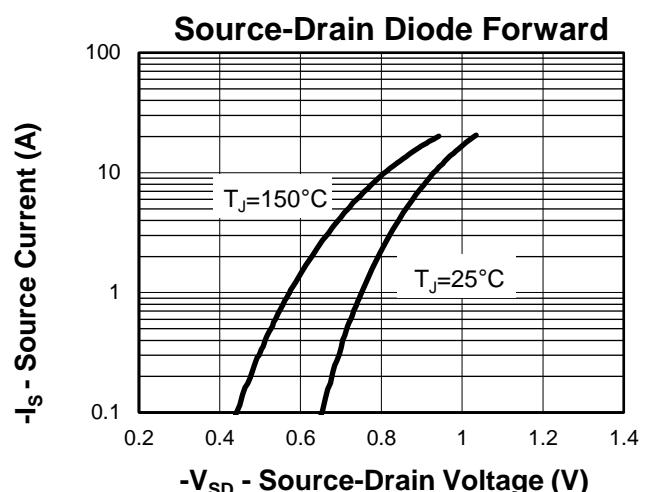
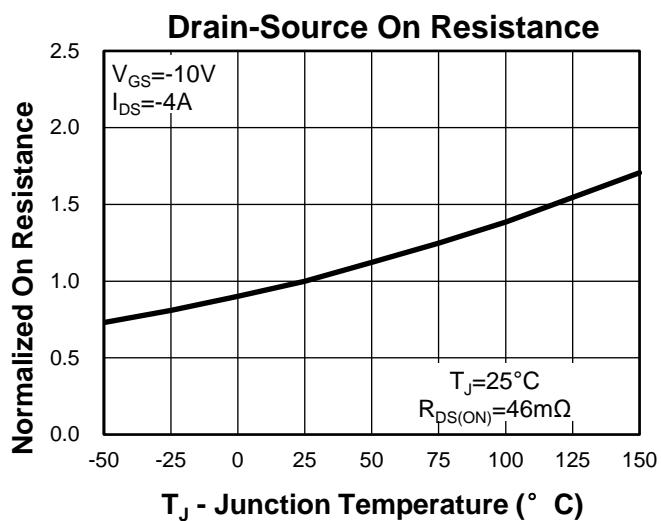
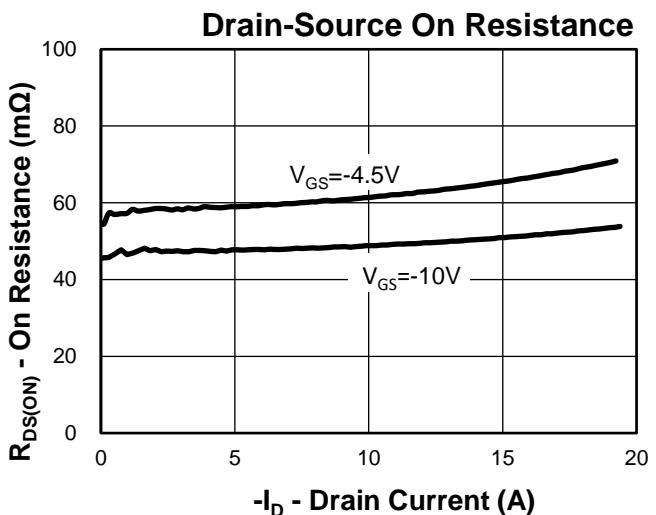
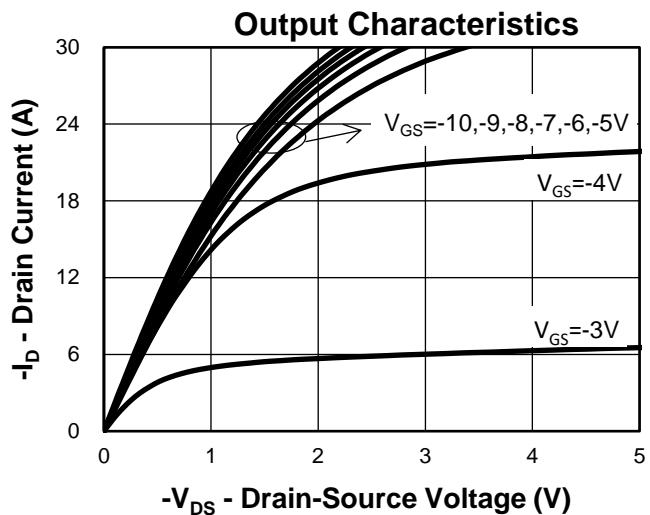
Typical Characteristics(N-Channel)



Typical Characteristics(P-Channel)

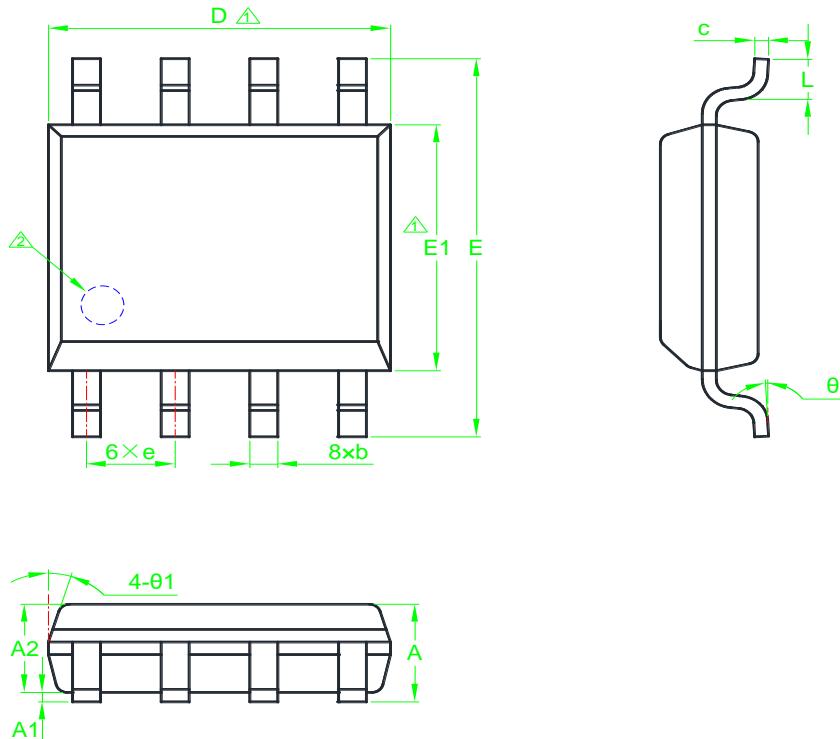


Typical Characteristics(P-Channel)



Package Information

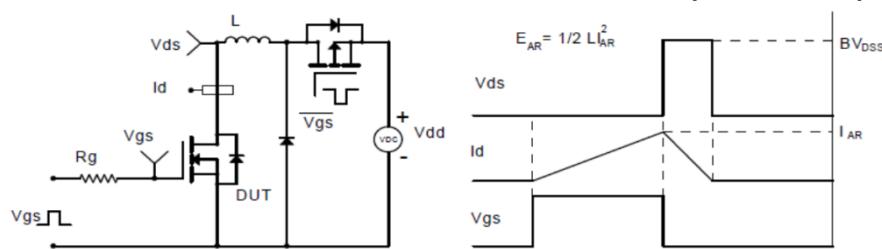
SOP8



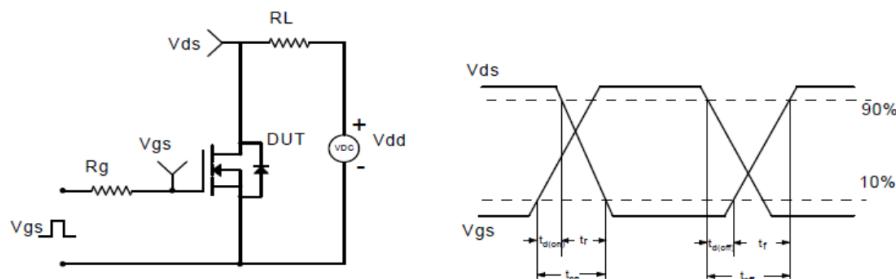
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.35	*	1.75	0.053	*	0.069
A1	0.10	*	0.25	0.004	*	0.010
A2	1.25	1.45	1.65	0.049	0.057	0.065
b	0.33	*	0.51	0.013	*	0.020
c	0.15	*	0.25	0.006	*	0.010
D	4.70	4.90	5.10	0.185	0.193	0.201
E	5.80	6.00	6.30	0.228	0.236	0.248
E1	3.80	3.90	4.00	0.150	0.154	0.157
e	1.27BSC			0.050BSC		
L	0.40	*	1.27	0.016	*	0.050
θ	0°	*	8°	0°	*	8°
θ 1	5°	*	15°	5°	*	15°

- 1 Dimensions D and E1 do not include mold flash protrusions or gate burrs.
- 2 The existence and size of demolding hole are variable depending on mold.

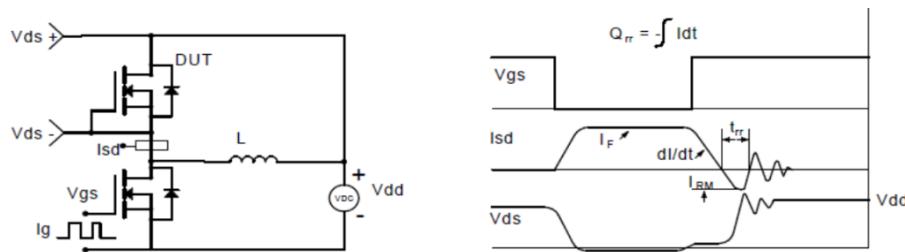
Avalanche Test Circuit and Waveforms(N-Channel)



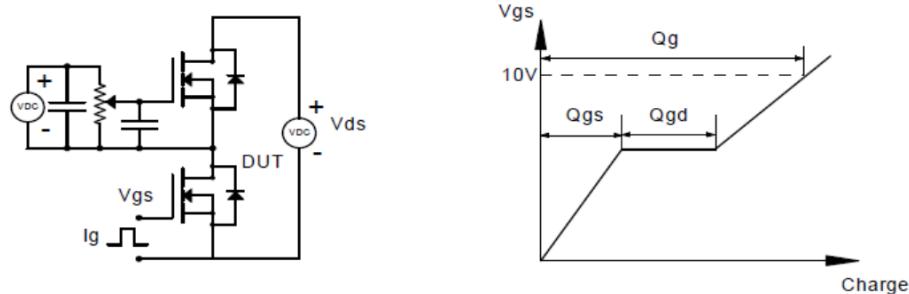
Switching Time Test Circuit and Waveforms(N-Channel)



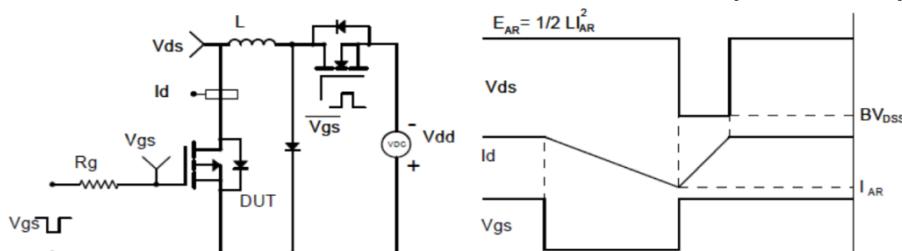
Diode Recovery Test Circuit and Waveforms(N-Channel)



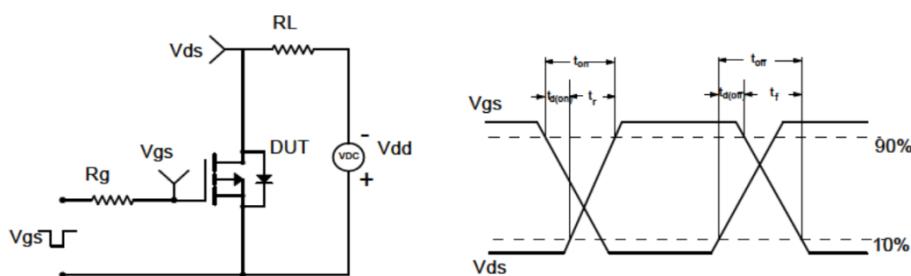
Gate Charge Test Circuit and Waveform(N-Channel)



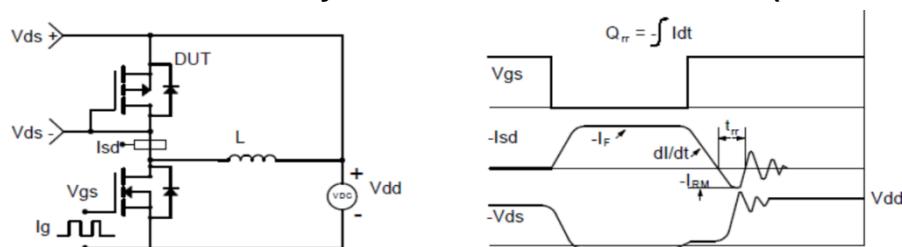
Avalanche Test Circuit and Waveforms(P-Channel)



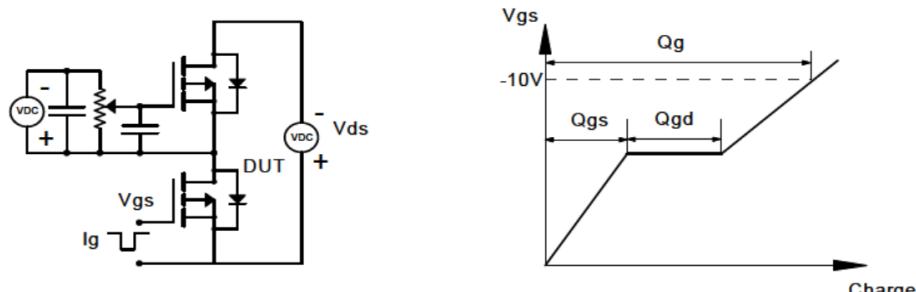
Switching Time Test Circuit and Waveforms(P-Channel)



Diode Recovery Test Circuit and Waveforms(P-Channel)



Gate Charge Test Circuit and Waveform(P-Channel)



Customer Service

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